

MP-5050-24XY

Mid Power LED



Features

- High efficacy
- CRI Options: Minimum 70, 80, 90
- Low thermal resistance
- Compatible with automatic placement equipment
- Compatible with infrared reflow solder process
- Coating process for superior sulfur resistance



Applications

- Traditional lighting replacement
- Indoor&Outdoor sign board back light
- Ordinary lighting
- Architectural lighting

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Ordering Information

Ordering Part Numbers^{1,2}

Minimum CRI	CCT	Luminous Flux		Ordering Part Number
		Minimum Flux (lm)	Maximum Flux (lm)	
70	2700K	210	220	MP-5050-24XY-27-70M
80		200	210	MP-5050-24XY-27-80M
90		180	190	MP-5050-24XY-27-90M
70	3000K	220	230	MP-5050-24XY-30-70M
80		210	220	MP-5050-24XY-30-80M
90		190	200	MP-5050-24XY-30-90M
70	3500K	220	230	MP-5050-24XY-35-70M
80		210	220	MP-5050-24XY-35-80M
90		190	200	MP-5050-24XY-35-90M
70	4000K	230	240	MP-5050-24XY-40-70M
80		220	230	MP-5050-24XY-40-80M
90		200	210	MP-5050-24XY-40-90M
70	5000K	230	240	MP-5050-24XY-50-70M
80		220	230	MP-5050-24XY-50-80M
90		200	210	MP-5050-24XY-50-90M
70	5700K	230	240	MP-5050-24XY-57-70M
80		220	230	MP-5050-24XY-57-80M
90		200	210	MP-5050-24XY-57-90M
70	6500K	230	240	MP-5050-24XY-65-70M
80		220	230	MP-5050-24XY-65-80M
90		200	210	MP-5050-24XY-65-90M

Notes:

1. Test condition : $I_f = 180 \text{ mA}$, $T_c = 25^\circ\text{C}$.
2. M3 ANSI ≤ 3 SCDM; M5 ANSI ≤ 5 SCDM.

Ordering Information

Part Number Nomenclature

MP

5050

24XY

##

##

Product Family	Package Type	Package Configurator	Nominal CCT ¹	Minimum CRI
MP: Mid Power LED	5050: 5.0 mm x 5.0 mm	24XY: Package code	27: 2700K 30: 3000K 35: 3500K 40: 4000K 45: 4500K 50: 5000K 65: 6500K	70M: CRI>70, EMC 80M: CRI>80, EMC 90M: CRI>90, EMC

Note:

1. Correlated Color Temperatures (CCT)



Binning Structure

Each mid power product shipped will be labeled with its specific flux and voltage bins. Not all bins listed are available in all CCTs and CRIs.

Flux Bins¹

Flux Bin	Binning @ 180 mA, T _c = 25°C	
	Minimum Flux (lm)	Maximum Flux (lm)
X40	180	190
X41	185	190
X42	190	200
X43	195	200
X44	200	210
X45	205	210
X46	210	220
X47	220	230
X48	230	240

Forward Voltage Bins

Voltage Bin	Binning @ 180 mA, T _c = 25°C	
	Minimum Voltage (V)	Maximum Voltage (V)
Y2-0	5.4	5.6
Y2-1	5.6	5.8
Y2-2	5.8	6.0
Y2-3	6.0	6.2

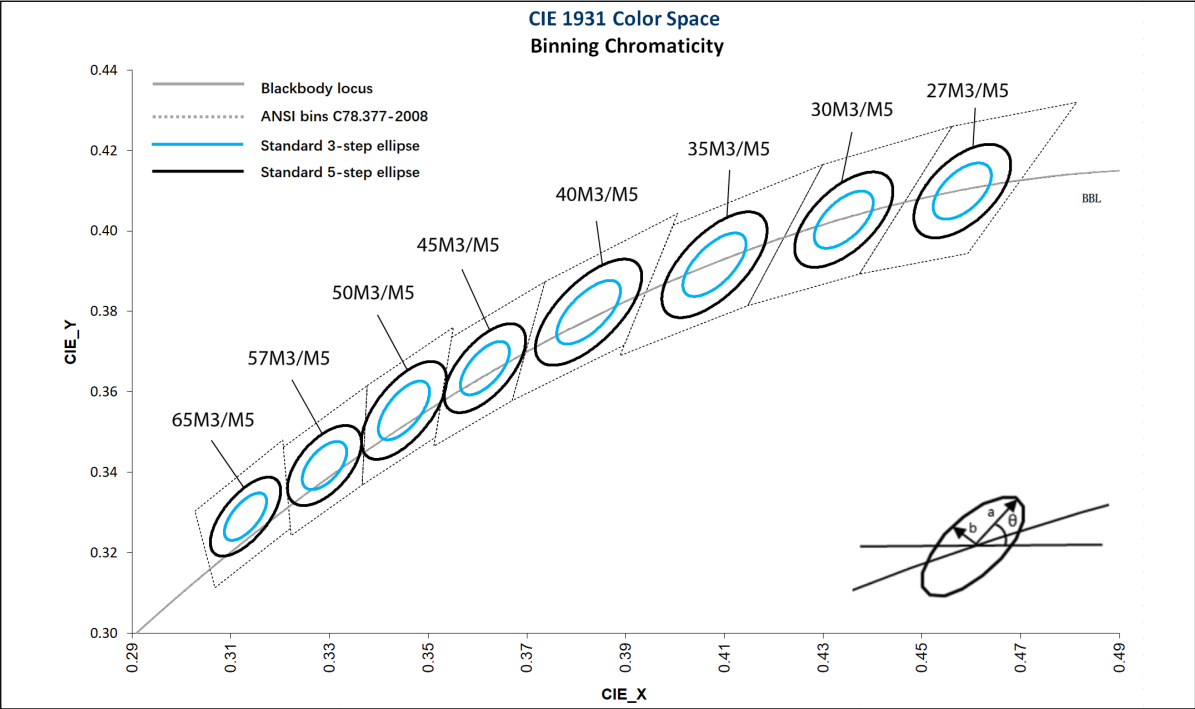
Note:

1. Luminus maintains a ±6% tolerance on flux measurement.



Binning Structure

Chromaticity Binning Diagram



Chromaticity Bin¹ ($I_f = 180 \text{ mA}$, $T_c = 25^\circ\text{C}$)

CCT	Center point		3-step Bin		5-step Bin		Angle (deg)
	x	y	a	b	a	b	Φ
2700K	0.4582	0.4099	0.00810	0.00420	0.01350	0.00700	53.42
3000K	0.4342	0.4028	0.00834	0.00408	0.01390	0.00680	53.13
3500K	0.4080	0.3916	0.00927	0.00414	0.01545	0.00690	54.00
4000K	0.3825	0.3798	0.00939	0.00402	0.01565	0.00670	53.43
4500K	0.3615	0.3659	0.00756	0.00338	0.01260	0.00563	57.58
5000K	0.3451	0.3554	0.00822	0.00354	0.01370	0.00590	59.37
5700K	0.3290	0.3417	0.00671	0.00330	0.01118	0.00550	58.35
6500K	0.3130	0.3290	0.00669	0.00285	0.01115	0.00475	58.34

Note:

1. M3 ANSI $\leq$ 3 SCDM; M5 ANSI $\leq$ 5 SCDM.



Absolute Maximum Ratings

Parameter	Symbol	Values	Unit
Maximum operating current	I_f	800	mA
Pulse Forward Current ^{1,2}	I_{fp}	960	mA
Power Dissipation	P_d	1000	mW
Maximum power	P_d	5000	mW
Reverse Voltage	V_r	10	V
Thermal Resistance (junction to case)	$R_{th J-C}$	2	°C/W
Case Temperature	T_c	105	°C
Junction Temperature	T_j	125	°C
Operating Temperature Range	T_{opr}	-40 to 85	°C
Storage Temperature Range	T_{stg}	-40 to 85	°C
Soldering Temperature	T_{sld}	260 °C for 10 sec	

Notes:

1. Frequency 10 KHz, duty ratio ≤10 %.
2. The forward pulse current is the maximum current used by the chip at 25°C.



Characteristics

Parameter ($I_f = 180 \text{ mA}$, $T_c = 25^\circ\text{C}$)		Symbol	Value	Unit
Forward Voltage	Minimum	$V_{f \text{ min}}$	5.4	V
	Maximum	$V_{f \text{ max}}$	6.2	
Viewing Angle		$2\theta_{1/2}$	120	°
ESD withstand Voltage ANSI/ESDA/JEDEC JS-001 (HBM)		V_{ESD}	2000	V

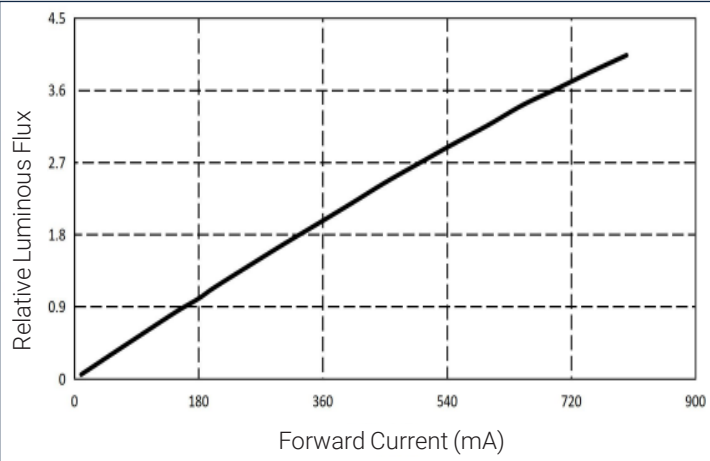
Notes:

1. To prevent damage refer to operating conditions and derating curves for appropriate maximum operating conditions.
2. Maximum operating case temperature combined with maximum drive current defines the total maximum operating condition for the device.
To prevent damage, please follow derating curves for all operating conditions.
3. Mid power LEDs are designed for operation up to an absolute maximum forward drive current as specified below. Product lifetime data is specified at typical forward drive currents. Sustained operation at absolute maximum currents will result in a reduction of device lifetime compared to typical forward drive currents. Actual device lifetimes will also depend on case temperature. Refer to the current vs. case temperature derating curves for further information.



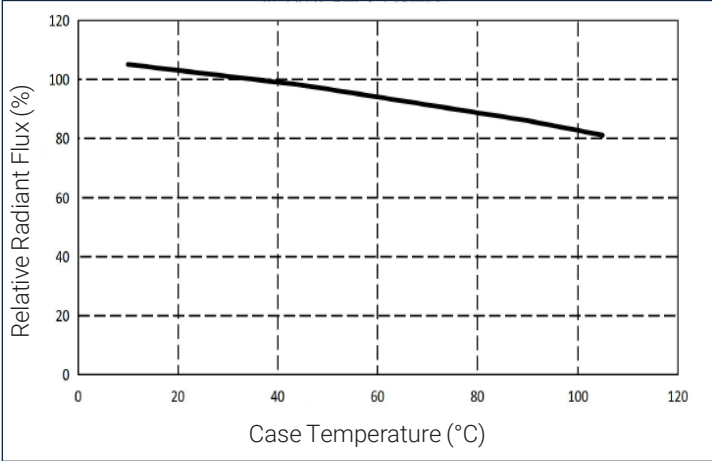
Relative Luminous Flux vs Forward Current

T_c = 25°C



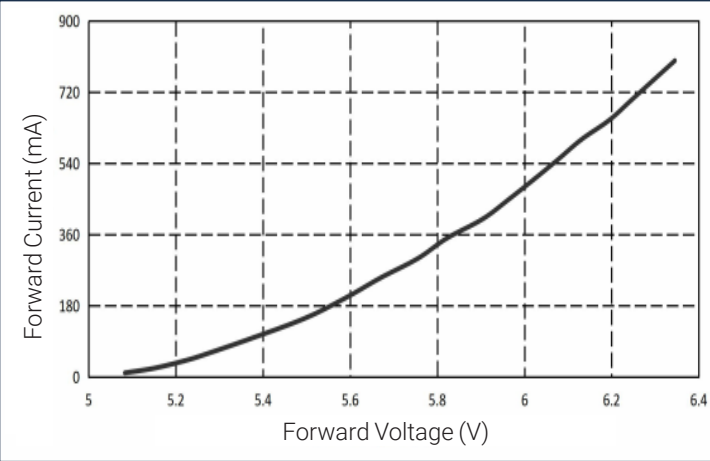
Relative Radiant Flux vs Temperature

I_f = 180 mA



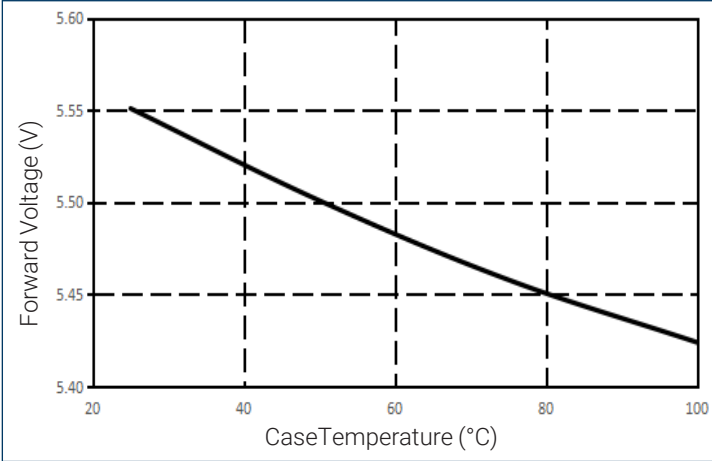
Forward Current vs Forward Voltage

T_c = 25°C

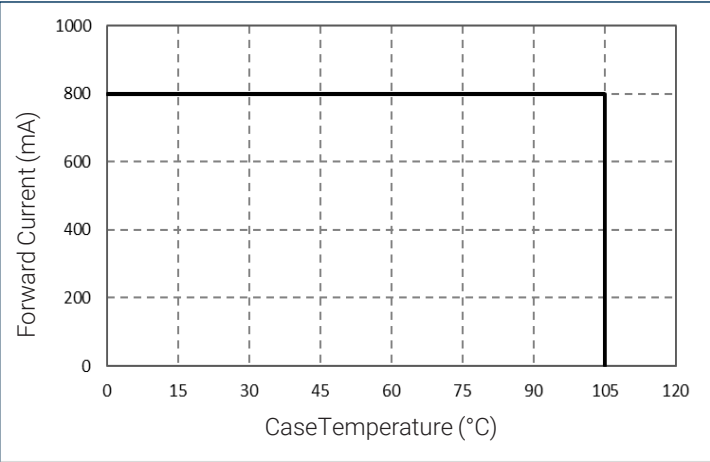


Forward Voltage vs Temperature

I_f = 180 mA



Forward Current vs Temperature

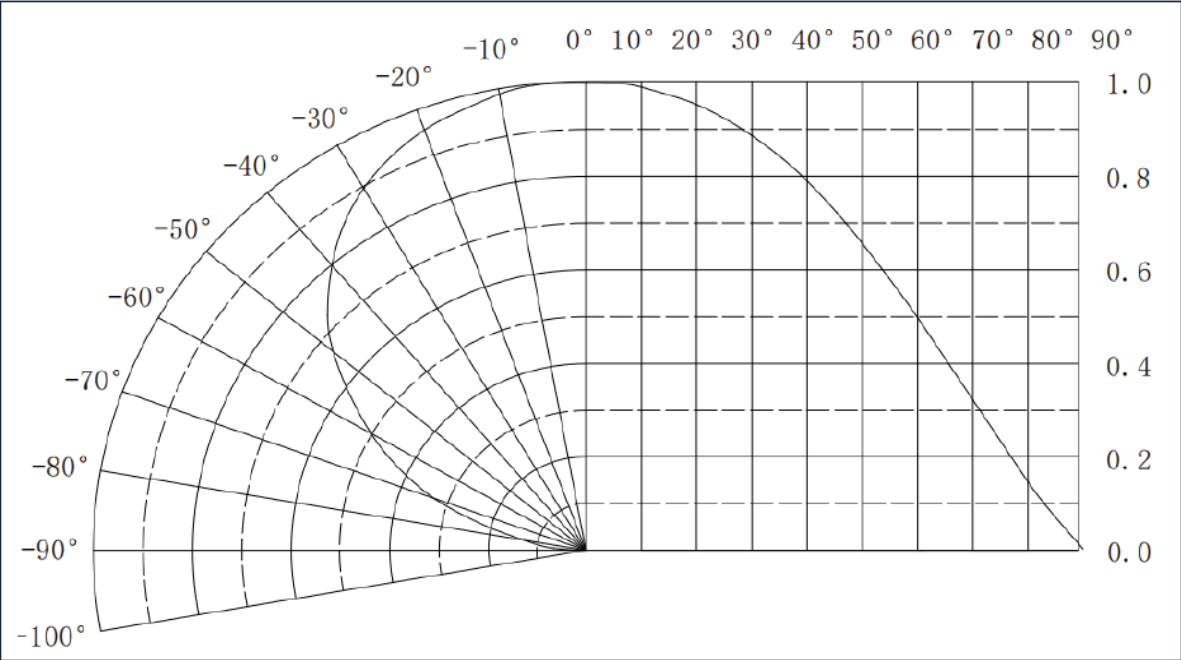




Angular Distribution and Typical Spectrum

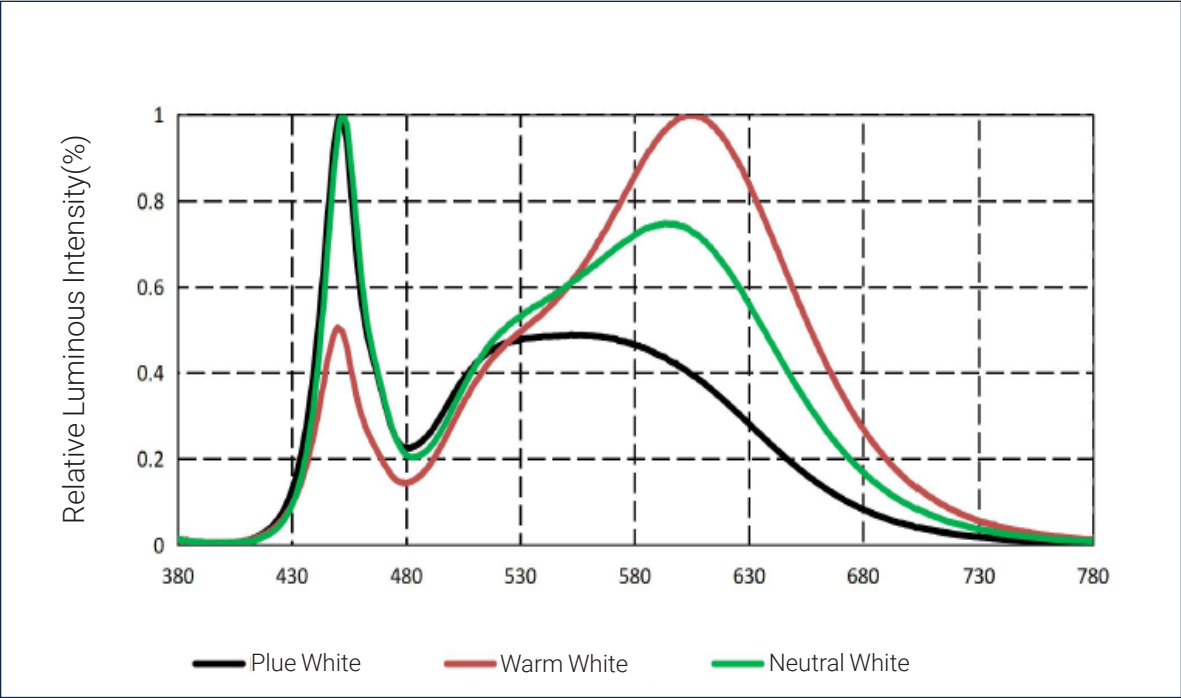
Angular Distribution

$T_c = 25^{\circ}\text{C}$



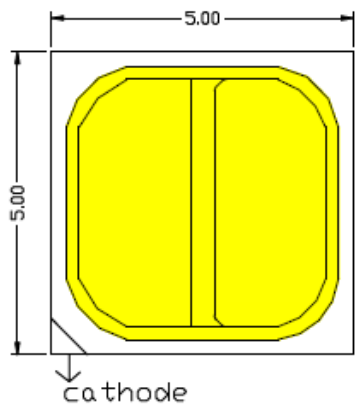
Relative Spectral Power Distribution

$T_c = 25^{\circ}\text{C}$

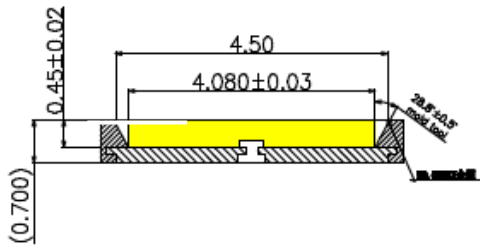




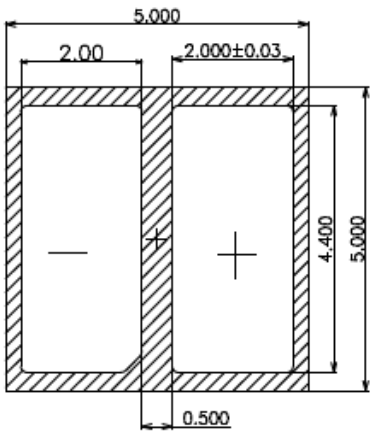
Mechanical Dimensions



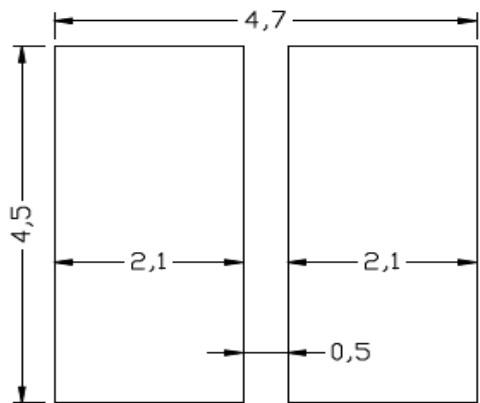
Top View



Side View



Perspective View



Recommended Solder Pad Design

Note:

1. All dimensions are in millimeter ± 0.15 mm, unless otherwise noted.



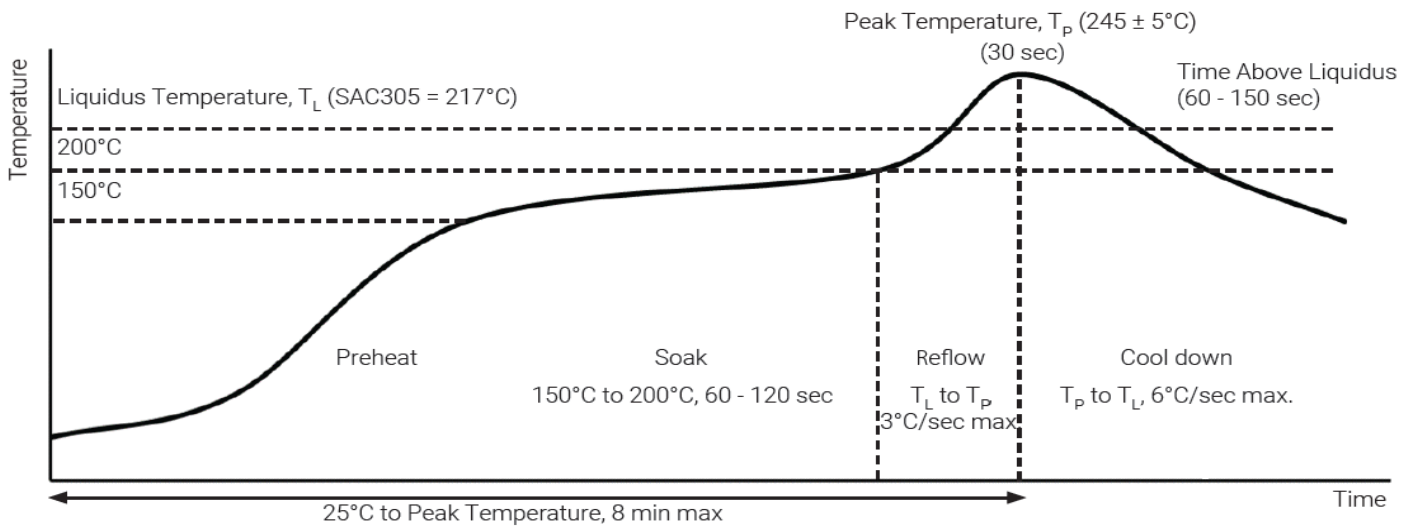
Mechanical Characteristics

JEDEC Moisture Sensitivity^{1, 2}

Level	Floor Life	
	Time	Conditions
3	168 Hours	≤30°C / 60% RH

- Notes:
- 1. Please note that the above MSL level based on the MSL qualification rating.
 - 2. This LED has silver-plated pads, and for LEDs with silver plating, MSL3 environment control is required to protect silver-plated surface from oxidation, even though the products may be qualified as MSL1 or 2.

Soldering Profile



SMT Solder Rework Temperature Guidelines

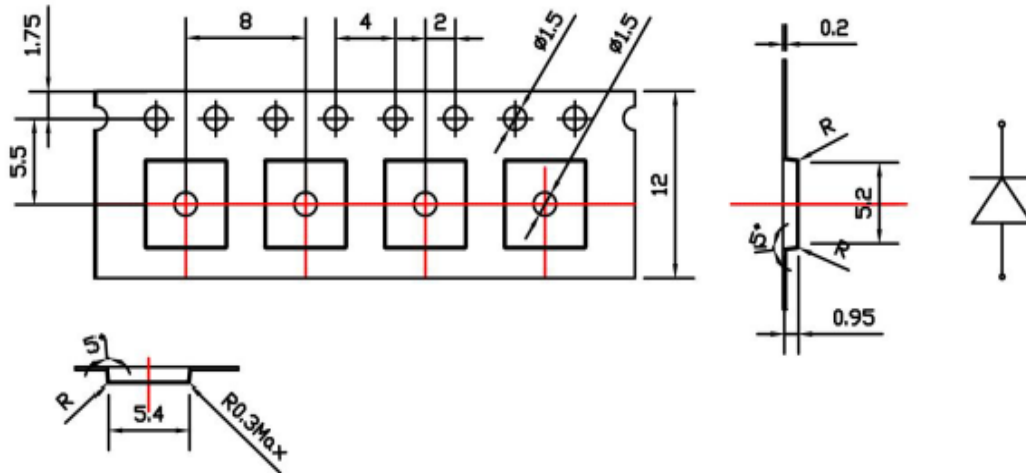
Parameter	Manual Hotplate Reflow	Hot Air Gun Reflow
Heating Time	< 60 sec	
Hotplate Temperature	< 245°C	< 150°C

Notes:

- The numbers in the table are specific to SAC305. Luminus recommends using an SAC305 solder paste with a no-clean flux for RoHS compliant products.
- Use of a multi-zone IR reflow oven with a nitrogen blanket is recommended.
- Time-temperature profile of the reflow process showing the four functional profile zones are defined in IPC-7801. All the temperatures refer to the application PCB measured adjacent to the package body.
- The actual profile shall be optimized per the PCB design and configuration.
- Key visual and LED performance characteristics to consider include solder bridging, solder voiding, solder balling, LED component placement or shifting, potential contamination that may impact light emissions, and the functional performance of the LED.
- Luminus recommends to use the solder paste data sheet information as a starting point in time-temperature process development.
- These are general guidelines. Consult the solder paste manufacturer's datasheet for guidelines specific to the alloy and flux combination used in your application. For more information, please refer to: <https://luminusdevices.zendesk.com/hc/en-us/articles/360060306692-How-do-I-Reflow-Solder-Luminus-SMD-Components->
- For any technical questions about soldering process, please contact Luminus at techsupport@luminus.com.

Tape and Reel Outline

Tape Package Dimensions



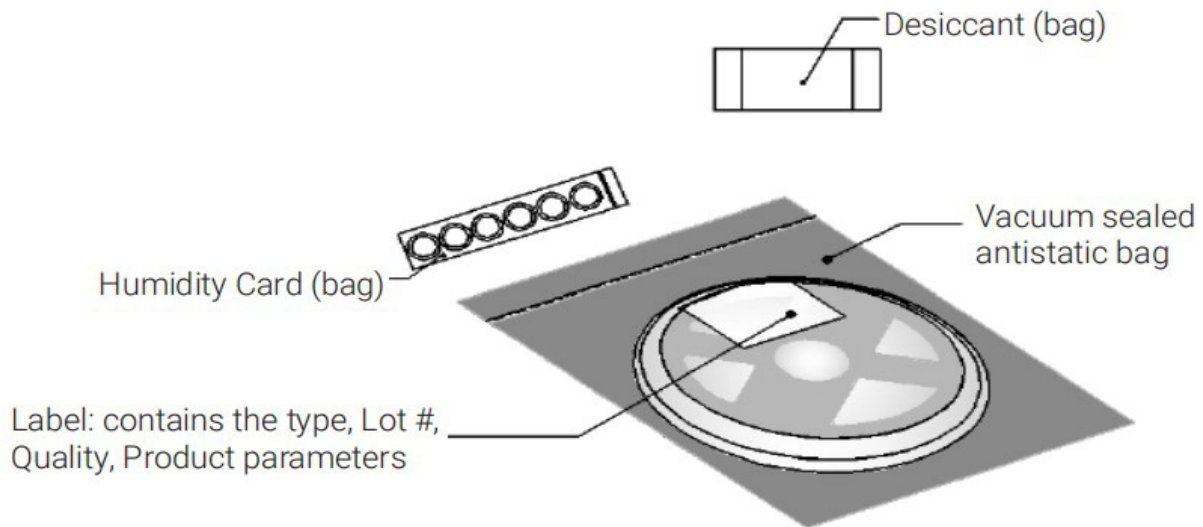
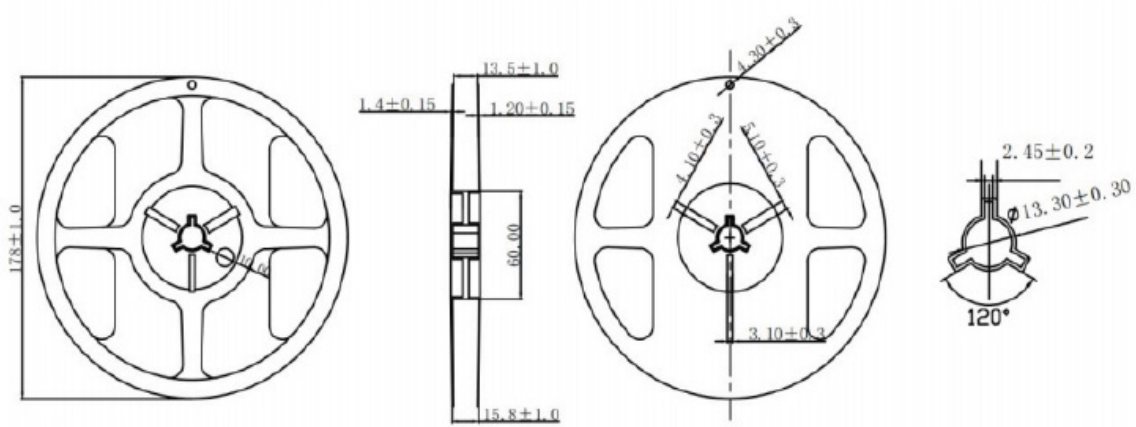
Notes:

1. Quantity: 2000 pcs per reel.
2. Cumulative Tolerance: Cumulative Tolerance/10 pitches to be ± 0.2 mm.
3. Adhesion Strength of Cover Tape Adhesion strength to be 0.1-0.7 N when the cover tape is pulled off from the carrier tape at the angle of 10° to the carrier tape.
4. Package: P/N, Manufacturing data Code No. and Quantity to be indicated on a damp proof package.
5. All dimensions are in millimeter.



Tape and Reel Outline

Reel Package Dimensions¹

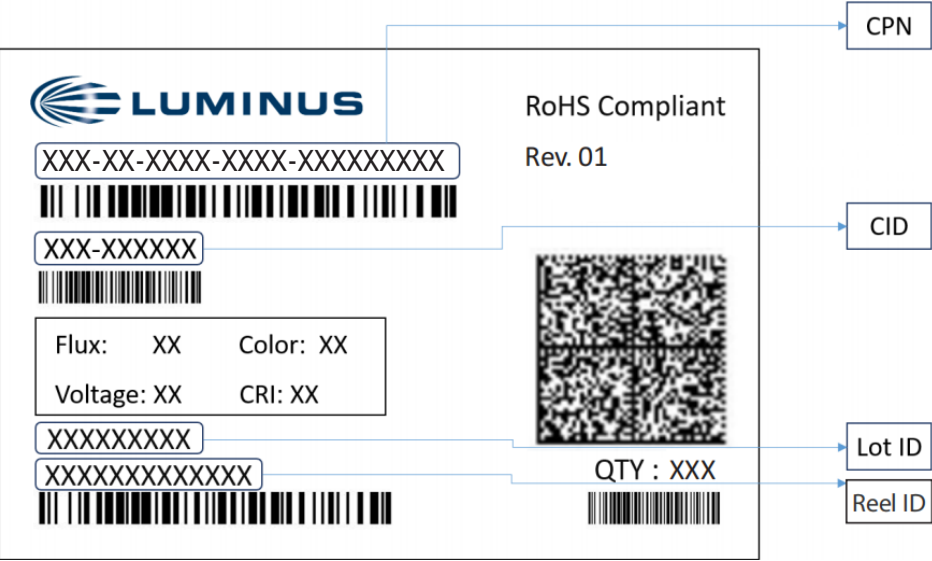


Note:

1. All dimensions are in millimeter.



Shipping Label



Label Fields:

- CPN: Luminus ordering part number
- CID: Customer's part number (this is a non-essential item)
- QTY: Quantity of parts per reel
- Flux: Bin as defined on page 4
- Voltage: Bin as defined on page 4
- Color: Bin as defined on page 5
- CRI: NA
- Lot ID & Reel ID: For Luminus internal use



Notes

Static Electricity

1. The products are sensitive to static electricity, and care should be taken when handling them.
2. Static electricity or surge voltage will damage the LEDs. It is recommended to wear an anti-electrostatic wristband or an anti-electrostatic gloves when handling the LEDs.
3. All devices, equipment and machinery must be properly grounded. It is recommended that measures be taken against surge voltage to the equipment that mounts the LEDs.

Storage

1. This device is rated at MSL 3 per JEDEC J-STD-020 standard.
2. Recommended storage condition: 5°C to 30°C and relative humidity 60 % RH in the original package.
3. After this bag is opened, devices that will be applied to infrared reflow, vapor phase reflow, or equivalent soldering process must be:
 - a) Completed within 168 hours
 - b) Stored at less than 60 %RH
 - c) If not completely used within 168 hours, seal the remaining in the moisture barrier bag.
4. Devices require baking before mounting, if 3 a) is not met.
5. If baking is required, devices must be baked under below conditions: 24 hours at 60°C±5°C.



Revision History

Rev	Date	Description of Change
01	05/19/2026	Initial release
02	08/06/2026	Update luminous flux and product photos